



# ThermoTek™

THERMAL MANAGEMENT SOLUTIONS

## PHASE PLANE™



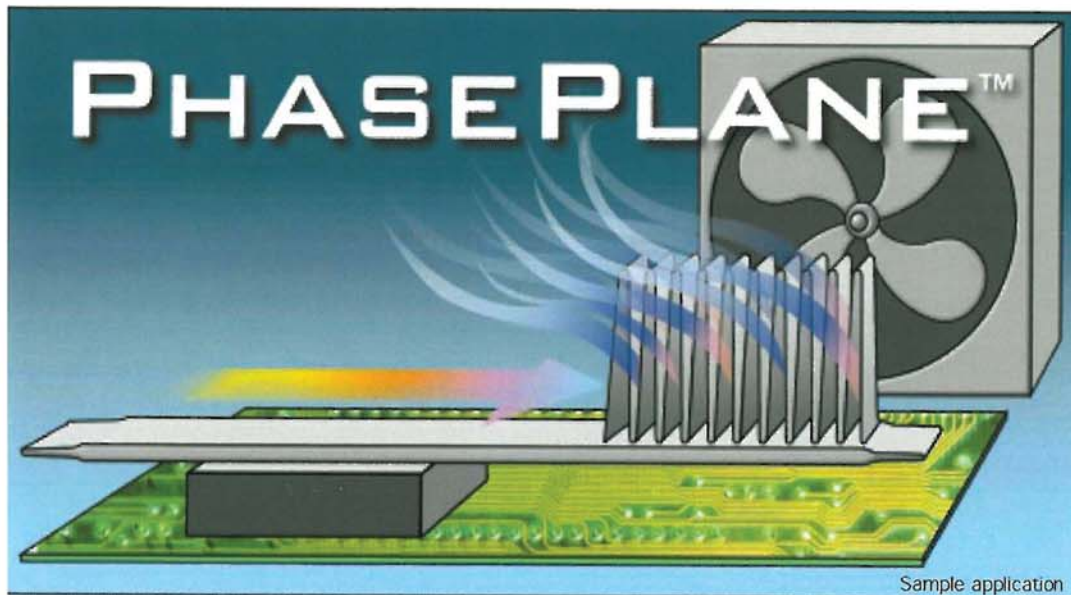
The low profile, patent-pending PhasePlane™ is for component level cooling applications. The form factor makes it ideal for applications on microprocessors, converters and other high watt density components.

### FEATURES:

- \* Lightweight - less than half the weight of the competitive product of same capacity.
- \* Uses include: Heat Pipe, Heat Spreader, Vapor Chamber, Heat Sink
- \* Minimized contact resistance, efficient Heat Transfer
- \* Horizontal to vertical operating envelope
- \* Flat form factor; welded construction
- \* Formable
- \* 2 Year Warranty
- \* Standard widths: 21mm, 31mm, 55mm
- \* Custom designs available.



**Patents:** [www.thermotekusa.com/patents](http://www.thermotekusa.com/patents)



### SAMPLE PERFORMANCE DATA

Sample Phase Plane Dimensions: 21mm x 4.2mm x 200mm

Horizontal Capacity: up to 46W

Vertical Capacity: up to 50W

Effective Thermal Conductivity: up to 7000 W/m K

Weight: 20.8g (average) without fins or mounting

Typical Flatness: 0.1mm per 10mm over the heat source

Material Composition: Aluminum

Fill Fluid: Acetone

Operating Temperature: -48°C to 100°C

Bend Radius: minimum of 12mm

Thermal Resistance: down to 0.32°C/W

**Note:** This sample performance data is from actual horizontal tests performed at 100°C by ThermoTek using a 21mm x 21mm lower heat source and a 21mm x 52mm upper condenser area. The above specifications are for reference only and will change for a specific application. Please provide ThermoTek the opportunity to review your application and select the best Phase Plane for you.



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